

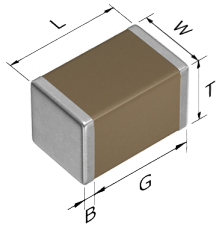


交货型号	C2012JB1E155MT****	
用途		一般等级
特点	<div>General</div>	一般（～75V）
系列	C2012 [EIA 0805]	
状态		量产体制(新设计非推荐)



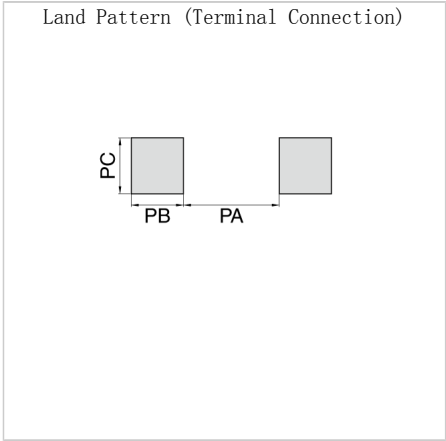
尺寸	
长度(L)	2.00mm ±0.20mm
宽度(W)	1.25mm ±0.20mm
厚度(T)	1.25mm ±0.20mm
端子宽度(B)	0.20mm Min.
端子间隔(G)	0.50mm Min.
推荐焊盘布局 (PA)	1.00mm to 1.30mm (Flow Soldering)
	0.90mm to 1.20mm (Reflow Soldering)
推荐焊盘布局 (PB)	1.00mm to 1.20mm (Flow Soldering)
	0.70mm to 0.90mm (Reflow Soldering)
推荐焊盘布局 (PC)	0.80mm to 1.10mm (Flow Soldering)
	0.90mm to 1.20mm (Reflow Soldering)

电气特性	
电容	1.5 μF ±20%
额定电压	25VDC
温度特性	JB (±10%)
耗散因数 (Max.)	5%
绝缘电阻 (Min.)	333M Ω

其他	
焊接方法	流体
	回流
AEC-Q200	NO
包装形式	塑封编带（180mm卷筒）
包装个数	2000pcs

特性图表 (这是参考数据，并不保证产品的特性。)

Associated Images



! Images are for reference only and show exemplary products.
! This PDF document was created based on the data listed on the TDK Corporation website.
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